

## HVU187

### Silicon Epitaxial Planar Pin Diode for High Frequency Attenuator

REJ03G0117-0500Z  
(Previous: ADE-208-054D)  
Rev.5.00  
Oct.08.2003

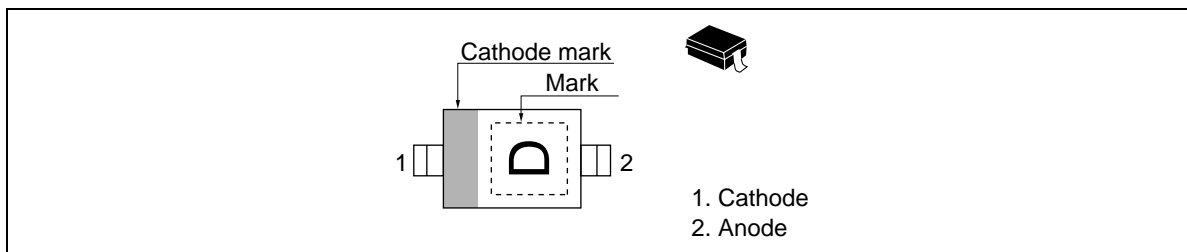
#### Features

- Low forward resistance. ( $r_f = 5.5 \Omega$  max)
- Ultra small Resin Package (URP) is suitable for surface mount design.

#### Ordering Information

Type No.	Laser Mark	Package Code
HVU187	D	URP

#### Pin Arrangement



### Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	60	V
Forward current	$I_F$	50	mA
Power dissipation	$P_d$	100	mW
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

### Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	$I_R$	—	—	100	nA	$V_R = 60\text{ V}$
Forward voltage	$V_F$	—	—	1.0	V	$I_F = 10\text{ mA}$
Capacitance	$C$	—	—	2.4	pF	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$
Forward resistance	$r_f$	3.5	—	5.5	$\Omega$	$I_F = 10\text{ mA}$ , $f = 100\text{ MHz}$
ESD-Capability *1	—	200	—	—	V	$C = 200\text{ pF}$ , Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion;  $I_R \geq 100\text{ nA}$  at  $V_R = 60\text{ V}$

Main Characteristic

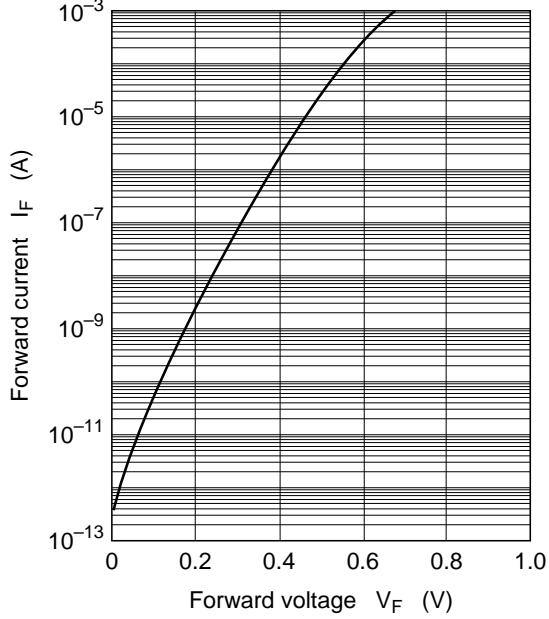


Fig.1 Forward current vs. Forward voltage

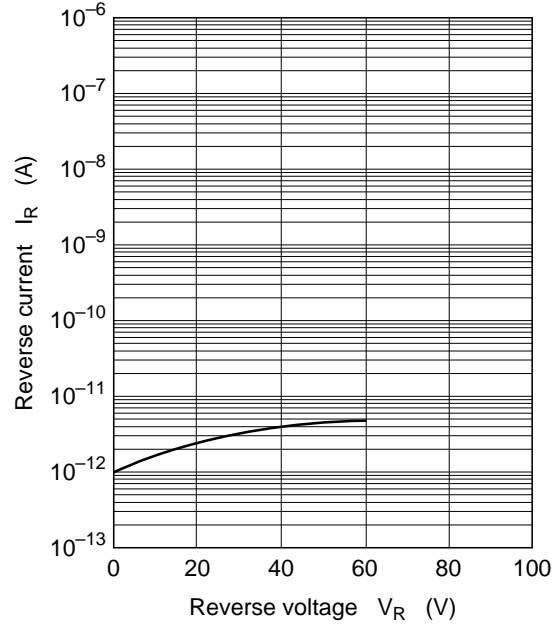


Fig.2 Reverse current vs. Reverse voltage

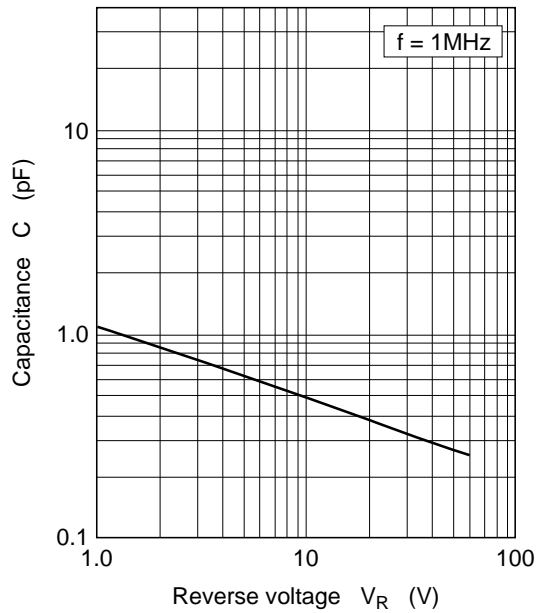


Fig.3 Capacitance vs. Reverse voltage

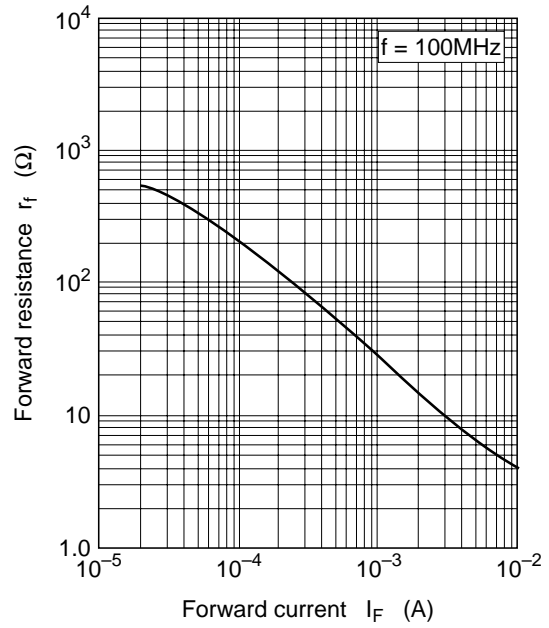
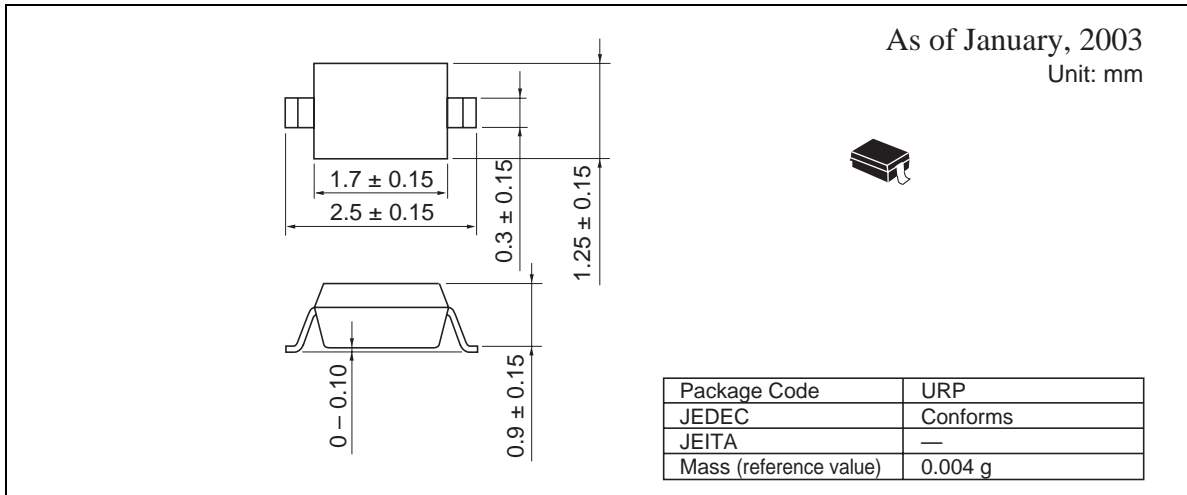


Fig.4 Forward resistance vs. Forward current

Package Dimensions



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